

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3831384

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	Fu-Cheng Yen	04/08/2016
	Tsung-Mu Yang	04/08/2016
	Sheng-Hsu Liu	04/08/2016
	Tsang-Hsuan Wang	04/08/2016
	Chun-Liang Kuo	04/08/2016
	Yu-Ming Hsu	04/08/2016
	Chung-Min Tsai	04/08/2016
	Yi-Wei Chen	04/08/2016
RECEIVING PARTY DATA		
Name:	UNITED MICROELECTRONICS CORP.	
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	
City:	Hsin-Chu City	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	15099581
CORRESPONDENCE DATA		
Fax Number:	(703)997-4517	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	3027291562	
Email:	Patent.admin.uspto.cr@naipo.com	
Correspondent Name:	WINSTON HSU	
Address Line 1:	P.O.BOX 506	
Address Line 4:	MERRIFIELD, VIRGINIA 22116	
ATTORNEY DOCKET NUMBER:	NAUP2703USA	
NAME OF SUBMITTER:	KATE YEY	
SIGNATURE:	/KATE YEY/	
DATE SIGNED:	04/14/2016	

Total Attachments: 16

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I hereby declare that:

This declaration is directed to:

☒ The attached application, or

☐ United States application number _____ filed on _____, or

☐ PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

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(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this **APR 08 2016** (Date of signing)

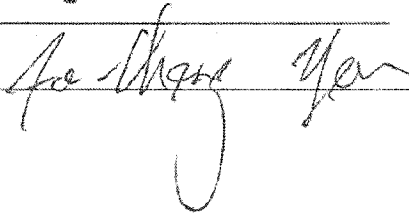
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Fu-Cheng Yen**

Date: **APR 08 2016**

Signature:

A handwritten signature in black ink, appearing to read 'Fu-Cheng Yen', written over a horizontal line.

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tsung-Mu Yang

Date: APR 08 2016

Signature: Tsung-Mu Yang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Sheng-Hsu Liu**

Date:

APR 08 2016

Signature:

Sheng-Hsu Liu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tsang-Hsuan Wang

Date: APR 08 2016

Signature: Wang, Tsang-Hsuan

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chun-Liang Kuo

Date:

APR 08 2016

Signature: Chun-Liang Kuo

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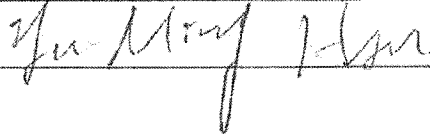
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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yu-Ming Hsu

Date: APR 08 2016

Signature:



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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chung-Min Tsai**

Date: **APR 08 2016**

Signature: Chung-Min Tsai

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